

OCP HPC Sub Project

Minutes - 06/13/2023

Meeting Transcript :

https://docs.google.com/document/d/1W_v15Q9X-8cA3u5oSiO_kIHs8_Nz-l5n/edit?usp=sharing&oid=111828941482233582910&rtpof=true&sd=true

Attendees

Attendee	Affiliation	06/13/2023
Phillipe Boisvert	Boyd	x
Kevin Cameron	Lightelligence	x
Allan Cante	Nallasway	x
Michael Choi	Samsung	x
Ender Demirel	DSTECH	x
Calum Devlin	CoolIT	x
Aras Drogan	MSBAI	x
Zaid Krisberg	SUNY Downstate Medical Center	x
John Leung	Intel	x
Andrea Moscheni	Vertive	x
Suresh Rejgopal	Micron	x
Darwesh Singh	Bolt Graphics	x
Mitch Wright	Individual	x
Victor		x
Totals		14

Meeting Objectives

Proposed Agenda for this meeting :

- 1) Introductions to New Attendees.
- 2) Update on offline Thermal Architecture Discussions
- 3) Update on Meeting with Oak Ridge National Labs, ORNL.
- 4) Conference discussion including BoF @ SC23 & OCP Global Summit submissions.
- 5) AOB

Meeting Discussion Notes

1) Introductions to New Attendees.

Aras Drogan - MSBAI - CFD Engineer and work in aerospace field, Work with Ender in thermal structures of designs. Interested in thermal modeling.

Andrea Moscheni - Vertiv - working as product manager for cooling units.

2) Update on offline Thermal Architecture Discussion

3) Update on Meeting with Oak Ridge National Labs, ORNL.

4) Conference discussion including BoF @ SC23 & OCP Global Summit submissions.

5) AOB

Tracking Actions

1.

Useful Links

Link to HPCM Specification - Working Document :

https://docs.google.com/document/d/1rsfMXx_ZPk489H28mmYmdVlpRx9EZQBgMjJ4wB3mx28/edit?usp=sharing